NPN High Voltage Transistor

The MMBT5551M3T5G device is a spin-off of our popular SOT-23 three-leaded device. It is designed for general purpose high voltage applications and is housed in the SOT-723 surface mount package. This device is ideal for low-power surface mount applications where board space is at a premium.

Features

- Reduces Board Space
- This is a Halide–Free Device
- This is a Pb–Free Device

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage	V _{CEO}	160	Vdc
Collector - Base Voltage	V _{CBO}	180	Vdc
Emitter-Base Voltage	V _{EBO}	6.0	Vdc
Collector Current – Continuous	Ι _C	60	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Мах	Unit
Total Device Dissipation FR-5 Board (Note 1) $T_A = 25^{\circ}C$ Derate above 25°C	P _D	265 2.1	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	470	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) T _A = 25°C Derate above 25°C	P _D	640 5.1	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	195	°C/W
Junction and Storage Temperature	T _J , T _{stg}	–55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

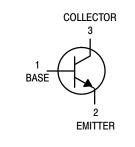
1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.

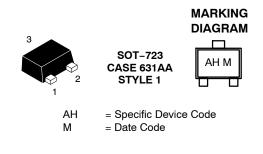
2. Alumina = 0.4 \times 0.3 \times 0.024 in. 99.5% alumina.



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http://onsemi.com





ORDERING INFORMATION

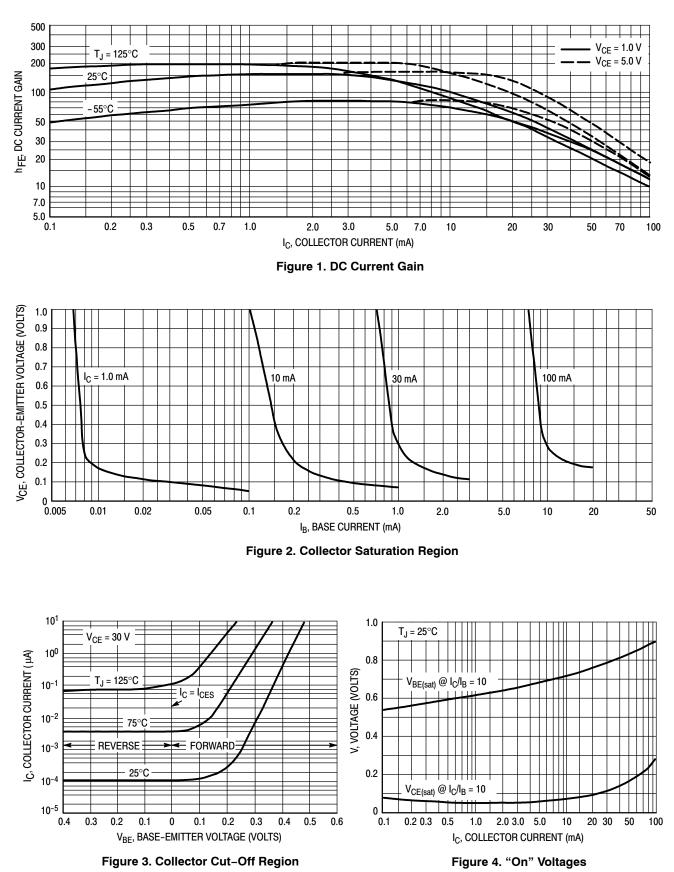
Device	Package	Shipping [†]
MMBT5551M3T5G	SOT-723 (Pb-Free)	8000/Tape & Reel

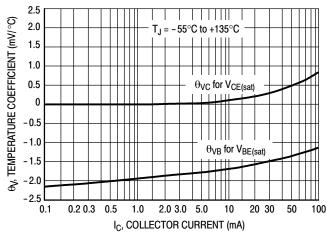
+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25° C unless otherwise noted)

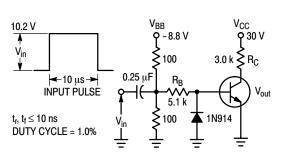
Characteristic	Symbol	Min	Мах	Unit
OFF CHARACTERISTICS				
Collector – Emitter Breakdown Voltage (Note 3) $(I_C = 1.0 \text{ mAdc}, I_B = 0)$	V _{(BR)CEO}	160	_	Vdc
Collector – Base Breakdown Voltage ($I_C = 100 \ \mu Adc, I_E = 0$)	V _(BR) CBO	180	_	Vdc
Emitter – Base Breakdown Voltage ($I_E = 10 \ \mu Adc, I_C = 0$)	V _{(BR)EBO}	6.0	-	Vdc
Collector Cutoff Current (V _{CB} = 120 Vdc, I _E = 0) (V _{CB} = 120 Vdc, I _E = 0, T _A = 100°C)	Ісво		100 100	nAdc μAdc
Emitter Cutoff Current (V _{EB} = 4.0 Vdc, I _C = 0)	I _{EBO}	-	50	nAdc
ON CHARACTERISTICS				
$ \begin{array}{l} \text{DC Current Gain} \\ (I_{C} = 1.0 \text{ mAdc}, V_{CE} = 5.0 \text{ Vdc}) \\ (I_{C} = 10 \text{ mAdc}, V_{CE} = 5.0 \text{ Vdc}) \\ (I_{C} = 50 \text{ mAdc}, V_{CE} = 5.0 \text{ Vdc}) \end{array} $	h _{FE}	80 80 30	_ 250 _	-
Collector – Emitter Saturation Voltage ($I_C = 10 \text{ mAdc}, I_B = 1.0 \text{ mAdc}$) ($I_C = 50 \text{ mAdc}, I_B = 5.0 \text{ mAdc}$)	V _{CE(sat)}		0.15 0.20	Vdc
Base – Emitter Saturation Voltage ($I_C = 10 \text{ mAdc}, I_B = 1.0 \text{ mAdc}$) ($I_C = 50 \text{ mAdc}, I_B = 5.0 \text{ mAdc}$)	V _{BE(sat)}		1.0 1.0	Vdc
Collector Emitter Cut-off $(V_{CB} = 10 \text{ V})$ $(V_{CB} = 75 \text{ V})$	ICES		50 100	nA

3. Pulse Test: Pulse Width = 300 μ s, Duty Cycle = 2.0%.

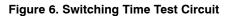


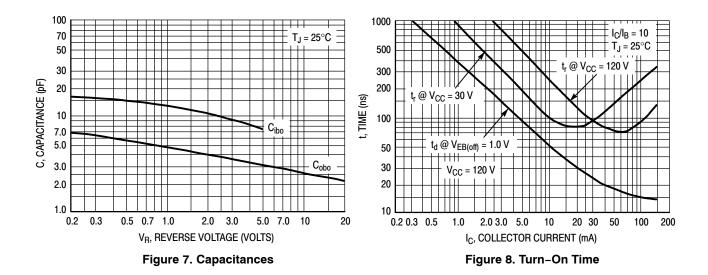


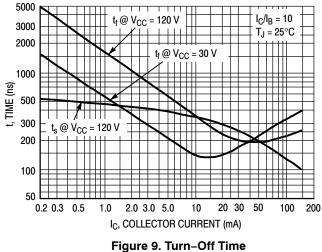




Values Shown are for $I_C \ensuremath{ @ 0 }$ 10 mA







PACKAGE DIMENSIONS

SOT-723 CASE 631AA-01 **ISSUE C**

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M. 1982.
- CONTROLLING DIMENSION: MILLIMETERS. MAXIMUM LEAD THICKNESS INCLUDES LEAD 2
- З. THICKNESS OF BASE MATERIAL. DIMENSIONS D AND E DO NOT INCLUDE MOLD
- 4. FLASH, PROTRUSIONS OR GATE BURRS.

	MILLIMETERS			ERS INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.45	0.50	0.55	0.018	0.020	0.022
b	0.15	0.21	0.27	0.0059	0.0083	0.0106
b1	0.25	0.31	0.37	0.010	0.012	0.015
С	0.07	0.12	0.17	0.0028	0.0047	0.0067
D	1.15	1.20	1.25	0.045	0.047	0.049
Е	0.75	0.80	0.85	0.03	0.032	0.034
е	0.40 BSC			0.016 BSC		
ΗE	1.15	1.20	1.25	0.045	0.047	0.049
L	0.15	0.20	0.25	0.0059	0.0079	0.0098

С Х Y STYLE 1:

-X-

b 2X

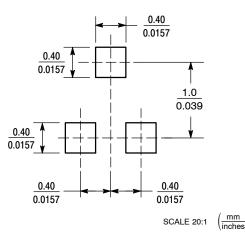
 \oplus

-Y-

0.08 (0.0032)

SOLDERING FOOTPRINT*

PIN 1. BASE 2. EMITTER 3. COLLECTOR



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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